S3	2613	(257/686).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2007/06/19 16:55
S4	1	("5917241").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2007/06/20 10:25
S5	625	solder adj ball and tape and 257/666	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2007/06/20 14:16
S6	1	("6455348").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2007/06/20 13:17
S7	1	"20030042581"	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2007/06/20 13:17
S8	0	solder adj ball and single adj sided adj tape and 257/666	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2007/06/20 14:18
S9	5	single adj sided adj tape and 257/666	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2007/06/20 16:28
S10	1	"20020008309"	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2007/06/20 16:36
S11	4060	lead adj frame and bond adj pad	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2007/06/21 07:42
S12	0	input and output and logis and 257/686	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2007/06/21 10:24

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L3	27754	(chip and (standoff or spacer))	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2007/06/24 13:08
L4	15911	exposed and L3	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2007/06/24 13:08
L5	2128	silicone and L4	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2007/06/24 15:41
L6	2578	semiconductor adj chip and (standoff or spacer) and package	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2007/06/24 18:15
L7	40	semiconductor adj chip and standoff.clm.	US-PGPUB	OR	ON	2007/06/24 18:18
L8	26	(257/e23.001).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2007/06/24 18:19
L9	1301	(257/e21.499).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2007/06/24 18:26
L10	1	semiconductor and mold$3 and silcon and standoff	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2007/06/24 18:26
S1	2043	wafer-to-wafer	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2007/06/19 16:55
S2	1	"20070018077"	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2007/06/18 12:37

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L3	27754	(chip and (standoff or spacer))	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2007/06/24 13:08
L4	15911	exposed and L3	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2007/06/24 13:08
L5	2128	silicone and L4	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2007/06/24 15:41
L6	2578	semiconductor adj chip and (standoff or spacer) and package	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2007/06/24 18:15
L7	40	semiconductor adj chip and standoff.clm.	US-PGPUB	OR	ON	2007/06/24 18:18
L8	26	(257/e23.001).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2007/06/24 18:19
L9	1301	(257/e21.499).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2007/06/24 18:26
L10	1	semiconductor and mold$3 and silcon and standoff	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2007/06/24 18:41
L11	1732	(257/706).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2007/06/24 18:41
S1	2043	wafer-to-wafer	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2007/06/19 16:55

S2	1	"20070018077"	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2007/06/18 12:37
S3	2613	(257/686).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2007/06/19 16:55
S4	1	("5917241").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2007/06/20 10:25
S5	625	solder adj ball and tape and 257/666	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2007/06/20 14:16
S6	1	("6455348").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2007/06/20 13:17
S7	1	"20030042581"	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2007/06/20 13:17
S8	0	solder adj ball and single adj sided adj tape and 257/666	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2007/06/20 14:18
S9	5	single adj sided adj tape and 257/666	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2007/06/20 16:28
S10	1	"20020008309"	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2007/06/20 16:36
S11	4060	lead adj frame and bond adj pad	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2007/06/21 07:42

S12	0	input and output and logis and 257/686	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2007/06/21 10:24
S13	422	input and output and logic and 257/686	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2007/06/21 11:48
S14	2	"20040095727"	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2007/06/21 11:57
S15	27754	(chip and (standoff or spacer))	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2007/06/21 11:58
S16	15911	exposed and S15	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2007/06/24 13:08

S13	422	input and output and logic and 257/686	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2007/06/21 11:48
S14	2	"20040095727"	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2007/06/21 11:57
S15	27754	(chip and (standoff or spacer))	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2007/06/21 11:58
S16	15911	exposed and S15	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2007/06/24 13:08